

**HSF** RoHS

NOTES:

1.MATERIAL:

- 1.1 Housing: thermoplastic plastics,
- 1.2 terminals:Copper Alloy  
Gold plated in contact area:  
Tin 40u"min plated in termination  
Nickel Plated overall
- 1.3 Shell:Steel&Copper Alloy  
Nickel/Tin Plated overall

2.ELECTRICAL CHARACTERISTICS:

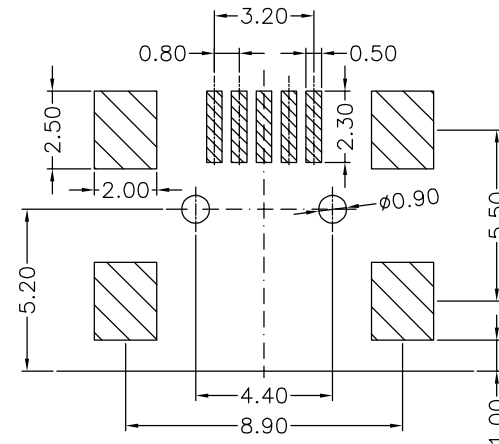
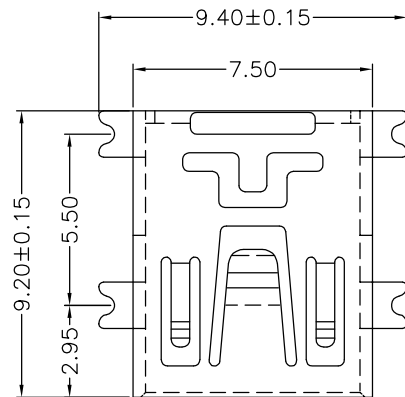
- 2.1 Rating Current :1.5 Ampere
- 2.2 Rating Voltage :30 V Max
- 2.3 Contact Resistance:50 Milli ohms
- 2.4 Insulation Resistance:100 Mega ohms Mi

3.MECHANICAL CHARACTERISTICS:

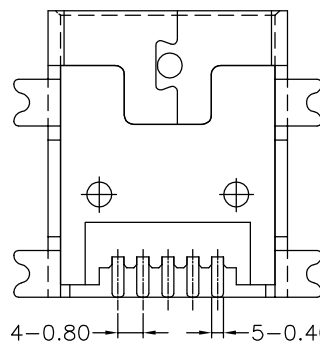
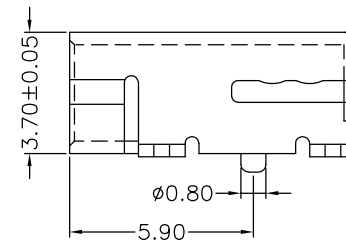
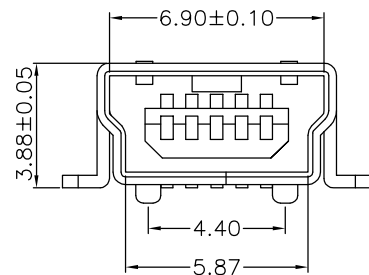
- 3.1 Connector Mating force: 35N MAX
- 3.2 Connector Unmating force:7N min

4.ENVIRONMENT CHARACTERISTICS:

- 4.1 Operating temperature:-0°C to +50°C
- 4.2 Storage temperature:-20°C to +60°C



RECOMMENDED PCB LAYOUT



**Ordering Information**

6233 - 05 FB M S0 B W A 01

Contact Plating  
G0:Gold Flash  
S0:Gold Flash/Tin  
S1:3U"Gold Flash/Tin  
S2:5U"Gold Flash/Tin  
SN:Tin

Insulator Color  
B=Black

OPERATION		DRAW	ChenWei	19.09.17	SCALE	FIT
X.X	±0.20				UNIT	mm
X.XX	±0.10	CHECK			SIZE	A4
X.XXX	±0.05				SHEET	1/1
Angle	±3°	APPROVE			PROJ.	客户名称:
DIM	TOL					



PART NO.	6233-05FBMS0BWA01
TITLE:	MINI USB 5P/F B型 SMT
客户名称:	

OPERATION	DRAW	ChenWei	19.09.17	SCALE	FIT
X.X	±0.20	CHECK			
X.XX	±0.10				
X.XXX	±0.05	APPROVE			
Angle	±3°				
DIM	TOL				

A0	2019.09.17	NEW DRAWING	
REV	DATE	MODIFICATION DESCRIPTION	CHANGE